

Features

- Low profile package
- Ideal for automated placement
- Glass passivated chip junction
- High forward surge capability
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C

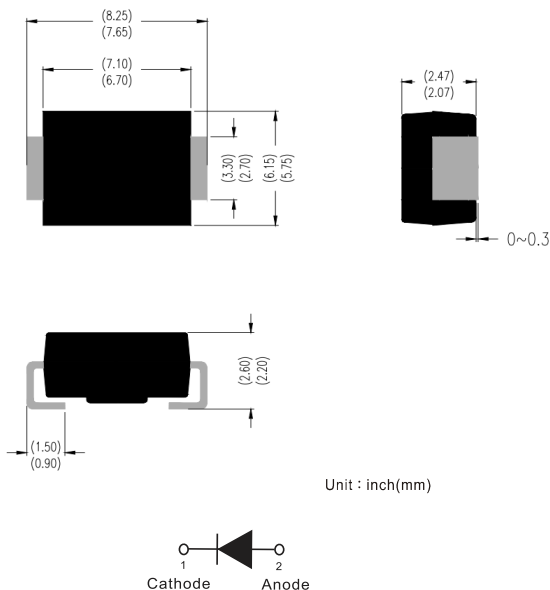
Typical Applications

For use in general purpose rectification of power supplies, inverters, converters, and freewheeling diodes for consumer, and telecommunication.

Mechanical Data

- Package: DO-214AB (SMC)
Molding compound meets UL 94 V-0 flammability rating, RoHS-compliant, halogen-free
- Terminals: Tin plated leads, solderable per J-STD-002 and JESD22-B102
- Polarity: Color band denotes the cathode end

DO-214AB (SMC)



■Maximum Ratings (T_a=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	GS3A	GS3B	GS3D	GS3G	GS3J	GS3K	GS3M
Maximum Repetitive peak reverse voltage	V _{RRM}	V	50	100	200	400	600	800	1000
Maximum RMS Voltage	V _{RMS}	V	35	70	140	280	420	560	700
Maximum DC Blocking Voltage	V _{DC}	V	50	100	200	400	600	800	1000
Average Rectified Output Current @60Hz sine wave, Resistance load, TL (FIG.1)	I _O	A	3.0						
Forward Surge Current (Non-repetitive) @60Hz Half-sine wave, 1 cycle, T _j =25°C	I _{FSM}	A	100						
Forward Surge Current (Non-repetitive) @1ms, square wave, 1 cycle, T _j =25°C			200						
Current squared time @1ms≤t≤8.3ms T _j =25°C	I ² t	A ² s	41.5						
Storage Temperature	T _{stg}	°C	-55 ~ +150						
Junction Temperature	T _j	°C	-55 ~ +150						

■Electrical Characteristics (T_a=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	TEST CONDITIONS	GS3A	GS3B	GS3D	GS3G	GS3J	GS3K	GS3M
Maximum instantaneous forward voltage	V _F	V	I _{FM} =3.0A	1.1						
Maximum DC reverse current at rated DC blocking voltage	I _R	μA	T _j =25°C	5						
			T _j =125°C	100						
Typical junction capacitance	C _j	pF	Measured at 1MHz and Applied Reverse Voltage of 4.0 V.D.C	25						

■ Thermal Characteristics (T_a=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	GS3A	GS3B	GS3D	GS3G	GS3J	GS3K	GS3M
Typical Thermal Resistance	R _{θJ-A} ⁽¹⁾	°C/W	48						
	R _{θJ-L} ⁽¹⁾		15						
	R _{θJ-C} ⁽¹⁾		12						

Note(1)

Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.6" x 0.6" (16 mm x 16 mm) copper pad areas

■ Characteristics(Typical)

FIG.1: I_o-T_L Curve

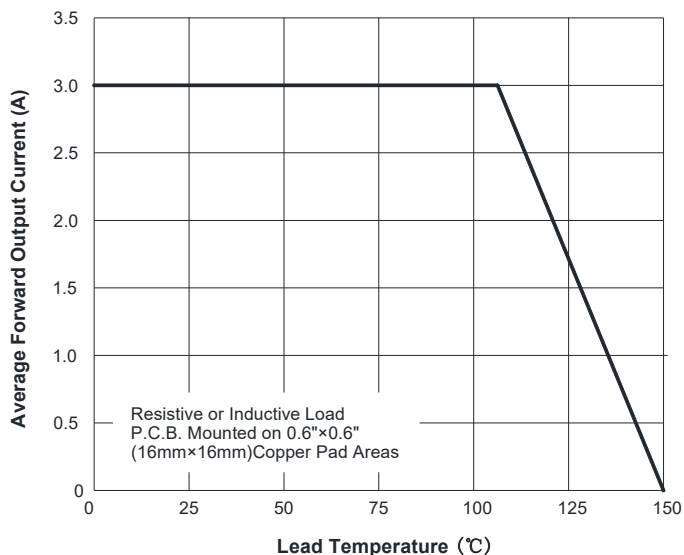


FIG.2: Forward Surge Current Capability

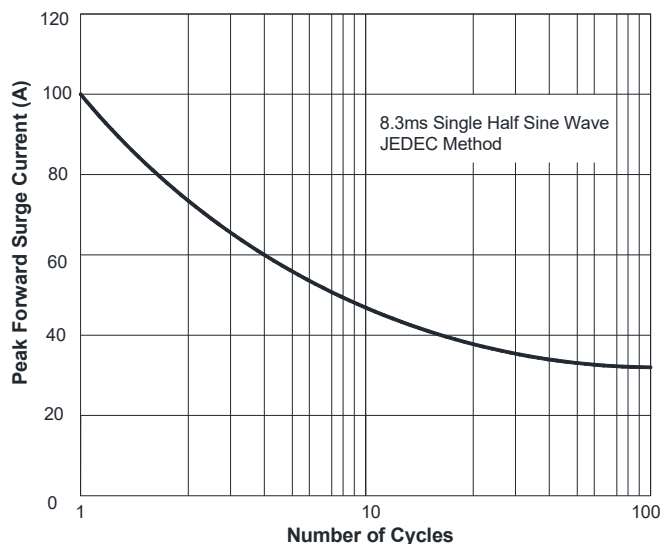


FIG.3: Typical Forward Voltage

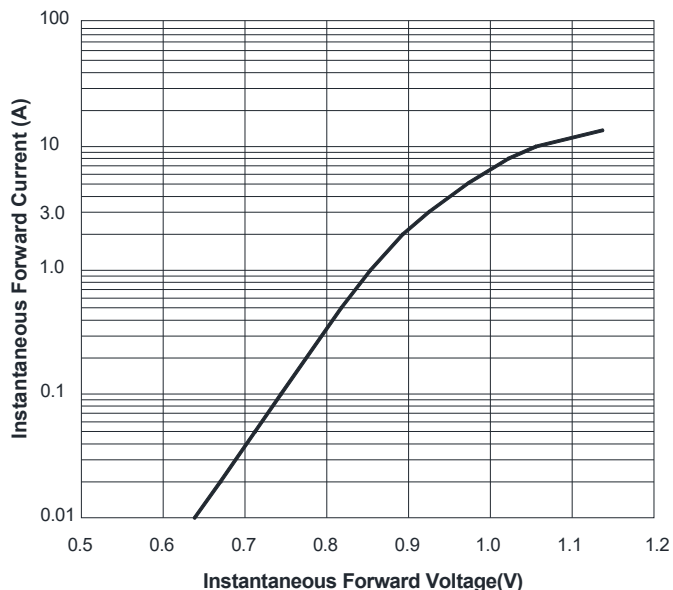


FIG.4: Typical Reverse Characteristics

